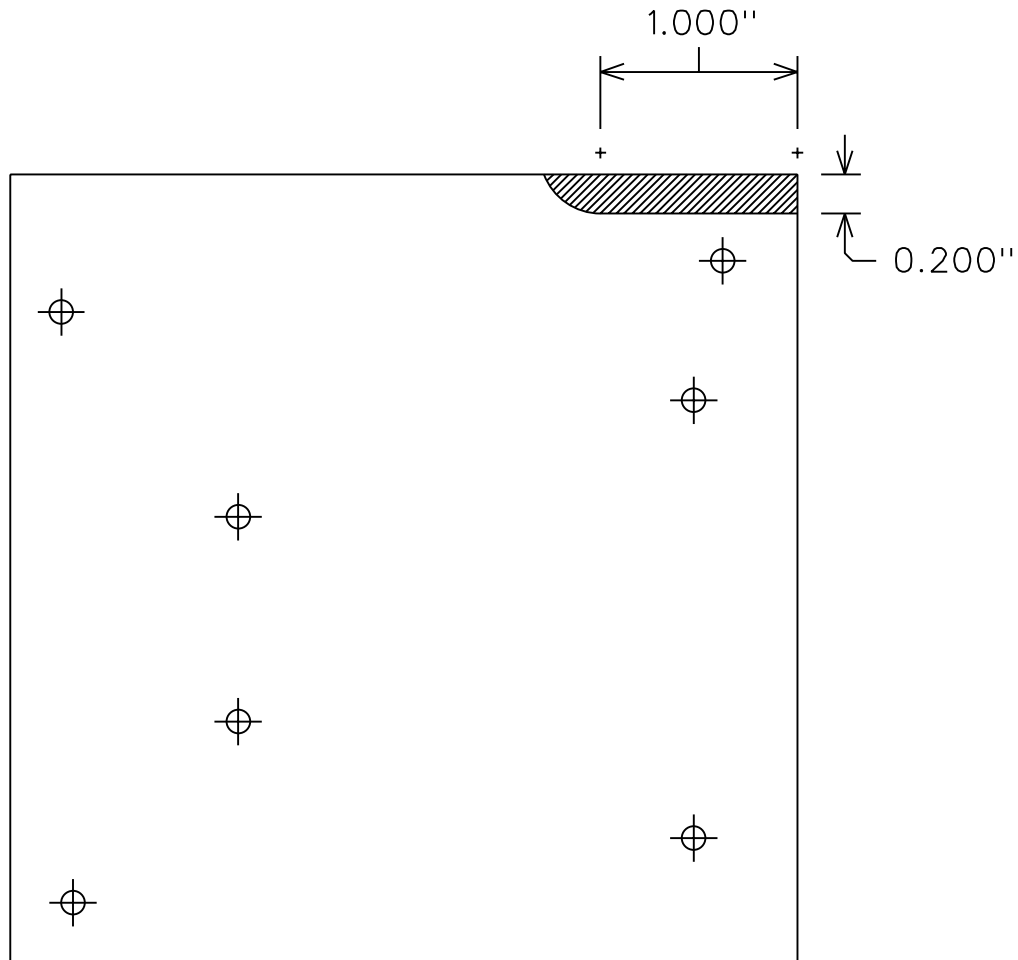


# Base Function FPGA Heatsink



This drawing is looking at the flat thermal contact side of the Base Function Heat Sink.

This drawing shows the area from which 30 mills should be removed from this flat side of the heat sink.

The tick marks show the motion of the center of a  $\frac{1}{2}$ " end-mill that could be used to remove this material.